IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	© Copyright 2005, IPC, E	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater						als and Mf	g Inform	nation	
Supplier Infor	mation														
Company name*			Company unique ID			τ	Unique ID Authority					Response Date*			
nsemi												2023-06-08			
Contact Name			Title - Contact			I	Phone - Contact*					Email - Contact*			
Product-Env-Stev	wards		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com			
authorized Repres	sentative*		Title - Representative			I	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Reques	ster Item Number	Mfr Item	Item Number Mfr Item Name				Effective Dat	te Versi	Version Manufacturing Site		ng Site	Weight*		UOM	Unit Type
		ESD5382MUT5G		ESD Protection Diode			2023-06-08		1	MY1		0.265		mg	Each
<b>Ianufacturing</b>	g Proccess Information														
Termina	Plating / Grid Array Material		Terminal Base Alloy		J-STD-020 MS	020 MSL Rating		Peak Process Body Temperature		Max Time at Peak Temper		Temperatu	nture Number of Reflow Cycles		eles
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 1		1		260		C	30 seco		second	s <b>3</b>		
Comments															
vel 1 - maximum	time at peak temperature d	uring solo	dering is 10-3	30 seconds			· · · · · · · · · · · · · · · · · · ·								
or more informat	tion regarding material com	position p	olease refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a						
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of				
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted				
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the				

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.013	mg	Supplier	Silicon (Si)	7440-21-3		0.013	mg
Die Attach	0.0189	mg	Supplier	Silver (Ag)	7440-22-4		0.0142	mg
			Supplier	Epoxy resins	129915-35-1		0.0047	mg
Lead Frame	0.1083	mg	Supplier	Tin (Sn)	7440-31-5		0.0003	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0002	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0003	mg
			Supplier	Copper (Cu)	7440-50-8		0.1075	mg
Mold Compound-Black	0.093	mg	Supplier	Epoxy and Phenolic Resin	40216-08-8		0.0074	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0005	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.0019	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.0804	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0028	mg
Plating	0.0269	mg	Supplier	Palladium (Pd)	7440-05-3		0.0025	mg
			В	Nickel (Ni)	7440-02-0		0.0243	mg
			Supplier	Gold (Au)	7440-57-5		0.0001	mg
Wire Bond - Au	0.0049	mg	Supplier	Gold (Au)	7440-57-5		0.0049	mg